

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND claim 2 in accordance with the following:

1. (WITHDRAWN) A packaging method for electronic parts comprising:  
forming an opening in a first substrate;  
laminating a second substrate on the first substrate;  
covering the opening with the second substrate;  
inserting a first electronic part into the opening and bonding the first electronic part to the second substrate;  
filling an interior of the opening with a resin to a fixed or larger thickness; and  
hardening the resin;  
wherein the first substrate and the first electronic part are thereby sustained by the resin, a second electronic part that should be connected to the first electronic part is bonded to a surface, on an exposed side, of the second substrate, and the first electronic part is connected to the second electronic part.

2. (CURRENTLY AMENDED) A packaging structure for electronic parts comprising:  
a first substrate having an opening;  
a second substrate laminated on the first substrate and covering the opening;  
a first electronic part inserted into the opening and bonded to the second substrate;  
a hard resin filling an interior of the opening;  
a second electronic part bonded to a surface, on an exposed side, of the second substrate;  
wiring for connecting the first electronic part to the second electronic part; and  
wherein the first substrate includes a sustaining member provided within the opening, bonded to an inner peripheral surface of the opening and sustaining an exposed surface of the resin.

3. (ORIGINAL) A packaging structure for electronic parts according to claim 2, wherein the second substrate is a thin film.

4. (ORIGINAL) A packaging structure for electronic parts according to claim 2, wherein the first electronic part is a capacitor, and the second electronic part is an LSI.

5. (ORIGINAL) A packaging structure for electronic parts according to claim 2, wherein the resin contains a filler agent.

6. (ORIGINAL) A packaging structure for electronic parts according to claim 2, wherein a coefficient of thermal expansion of the resin is adjusted according to the first and second substrates, and the first and second electronic parts.

7. (CANCELLED)

8. (PREVIOUSLY PRESENTED) A packaging structure for electronic parts according to claim 2, wherein a fin for cooling is bonded to the second electronic part.

9. (ORIGINAL) A packaging structure for electronic parts according to claim 2, wherein the second substrate has a stiffener for reinforcement.

10. (ORIGINAL) A packaging structure for electronic parts according to claim 9, wherein the stiffener is provided on the side of the first electronic part.

11. (ORIGINAL) A packaging structure for electronic parts according to claim 9, wherein the stiffener is provided on an outer peripheral edge of the thin film substrate.

12. (WITHDRAWN) A packaging method for electronic parts according to claim 1, wherein the second substrate is a thin film.

13. (WITHDRAWN) A packaging method for electronic parts according to claim 1, wherein the first electronic part is a capacitor, and the second electronic part is an LSI.

14. (WITHDRAWN) A packaging method for electronic parts according to claim 1,

wherein the resin contains a filler agent.

15. (WITHDRAWN) A packaging method for electronic parts according to claim 1, wherein a coefficient of thermal expansion of the resin is adjusted according to the first and second substrates, and the first and second electronic parts.

16. (WITHDRAWN) A packaging method for electronic parts according to claim 1, wherein the first substrate includes a sustaining member provided within the opening and sustaining an exposed surface of the resin.

17. (WITHDRAWN) A packaging method for electronic parts according to claim 16, wherein a fin for cooling is bonded to the second electronic part.

18. (WITHDRAWN) A packaging method for electronic parts according to claim 1, wherein the second substrate has a stiffener for reinforcement.

19. (WITHDRAWN) A packaging method for electronic parts according to claim 18, wherein the stiffener is provided on the side of the first electronic part.

20. (WITHDRAWN) A packaging method for electronic parts according to claim 18, wherein the stiffener is provided on an outer peripheral edge of the thin film substrate.